

IN THE CLAIMS

Please amend the claims as follows.

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15. (Currently Amended) A process for fabricating a bump, wherein the bump is disposed on a chip that has an active surface and at least a bonding pad, and the bonding pad exposes the active surface, the process comprising:

performing an activation step, depositing a medium layer on the bonding pad; and

performing an electroless plating process for forming at least a bump body on the medium layer ~~in an electroless plating way.~~

16. (Original) The process of claim 15, wherein a material of the bump body is nickel.

17. (Original) The process of claim 15, wherein a material of the medium layer is zinc.

18. (Original) The process of claim 15, before performing the activation step, further comprising a photolithography step, forming a photo resist layer on the chip, wherein the photo resist layer has at least an opening that exposes the bonding pad, and after forming the bump body, further comprising removing the photo resist layer from the chip.

19. (Original) The process of claim 15, after forming the bump body, further comprising forming a bump body passivation layer on the bump body covering the bump body except for a portion of the bump body that connects to the medium layer.

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20. (Original) The process of claim 19, wherein a material of the bump body  
passivation layer is gold.

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